IN THE CLAIMS:

Please amend the claims as follows:

1. *(currently amended)* A method for analysing connection conditions between an integrated circuit package and a circuit board, comprising the steps of:
   - ~~wherein~~ electrically coupling said integrated circuit package ~~is electrically coupled~~ to said circuit board by coupling elements, [[and]]
   - ~~wherein~~ mechanically connecting said integrated circuit ~~package is mechanically connected~~ with said circuit board by support elements,

   ~~characterised in that~~
   - electrically connecting at least two of said support elements with each other ~~are electrically connected to each other~~ on the side of the integrated circuit package,
   - picking-off physical values ~~are picked-off from~~ between said support elements, and
   - evaluating said physical values ~~are evaluated~~ to determine ~~the condition of said connection between said integrated circuit package and said circuit board.~~ mechanical properties if said support,
   - concluding a condition of said electrical coupling of said integrated circuit package with said circuit board from said determined mechanical properties of said support elements.

2. *(original)* The method of claim 1, wherein electrical values are picked-off from said support elements.

3. *(original)* The method of claim 1, wherein electrical resistance and/or electrical current and/or voltage within said support elements is picked-off.

4. *(original)* The method of claim 1, wherein mechanical values are picked-off from said support elements.

5. *(original)* The method of claim 1, wherein mechanical values are picked-off from said support elements using a strain gauge.

6. *(cancelled)*

7. *(original)* The method of claim 1, wherein said connection condition is determined in intervals.

8. *(original)* The method of claim 1, wherein said determined connection conditions are stored.

9. *(original)* The method of claim 1, wherein in case a poor connection condition is determined, a error message is generated.

10. *(original)* The method of claim 9, wherein said error message is presented on a user interface.

11. *(original)* The method of claim 9, wherein said error message is stored.

12. *(original)* The method of claim 9, wherein said error message is read out from a storage and used for maintenance.

13. *(currently amended)* A system for analysing connection conditions between an integrated circuit package and a circuit board, comprising:

- coupling elements coupling said integrated circuit package electrically to said circuit board, and
- support elements connecting said integrated circuit package mechanically with said

circuit board, ~~characterised by~~ wherein said system further comprises:

- means for electrically connecting at least two of said support elements with each other on the side of the integrated circuit package,
- measuring means arranged at said support elements ~~to pick-off~~ for picking-off physical values between [[from]] said support elements, and
- evaluation means for evaluating said physical values to determine ~~the condition of said connection between said integrated circuit package and said circuit board~~ mechanical properties of said support elements, and for concluding a condition of said electrical coupling of said integrated circuit package with said circuit board from said determined mechanical properties of said support elements.

14. *(original)* The system of claim 13, wherein said support elements are arranged between said circuit board and said integrated circuit package.

15. *(original)* The system of claim 13, wherein said support elements are solder pads.

16. *(original)* The system of claim 13, wherein said support elements are arranged adjacent to said coupling elements.

17. *(original)* The system of claim 13, wherein said support elements are arranged semicircular along said coupling elements.

18. *(original)* The system of claim 13, wherein said support elements are arranged along edges and/or at corners of said integrated circuit package.

19. *(original)* The system of claim 13, wherein said integrated circuit package is a chip scale package or a chip size package.

20. *(original)* The system claim 13, wherein said measuring means provide picking-off electrical conditions of said support elements.

21. *(original)* The system claim 13, wherein said measuring means provide picking-off mechanical conditions of said support elements.

22. *(original)* The system of claim 13, wherein storage means are comprised to store said picked-off physical values.

23. *(original)* The system of claim 13, wherein said evaluation means compare said picked-off physical values with comparative values to determine connection condition.

24. *(original)* The system of claim 13, wherein said evaluation means provide an error message in case a poor connection condition is determined.

25. *(original)* The system of claim 13, wherein said error message is stored within said storage means.

26. *(original)* The system of claim 13, wherein an interface is provided to read out said stored physical values and/or stored error messages.

27. *(original)* Consumer electronic device, in particular a mobile phone, comprising a system of claim 13.

28. *(original)* Computer program operable to cause a processor to analyse connection conditions between an integrated circuit package and a circuit board according to a method of claim 1.

29. *(original)* Computer program product comprising a computer program operable to cause a processor to analyse connection conditions between an integrated circuit package and a circuit board according to a method of claim 1.